



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Attorney Docket No.: 147268.00254

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TECHNOLOGY CENTER 2800

Group Art Unit: 2814

Examiner: Dilinh P. Nguyen

Inventors: Jung-Yu Lee *et al.*

Serial No.: 09/746,018

Filed: December 26, 2000

For: STRUCTURE OF HEAT SLUG-EQUIPPED PACKAGES AND THE PACKAGING METHOD OF THE SAME

AMENDMENT

APPLICANTS'
RESPONSIVE
AMENDMENT-B

Hon. Commissioner of Patents
And Trademarks
Washington, D.C. 20231

Sir:

In response to the Office Action mailed September 25, 2002, to which a response is due without extension by December 25, 2002, please amend the above-identified application as follows.

IN THE SPECIFICATION:

Please amend the paragraph at page 6, lines 14 through 19, to correct an obvious typographical error as follows:

One end of the bonding wire is connected to the chip 22 via a conductive pad formed thereon, the other end of the bonding wire 26 is connected to a solder ball of a BGA array 28 formed on the lower-sided surface (second major surface) of the substrate 20 via the conductive traces.